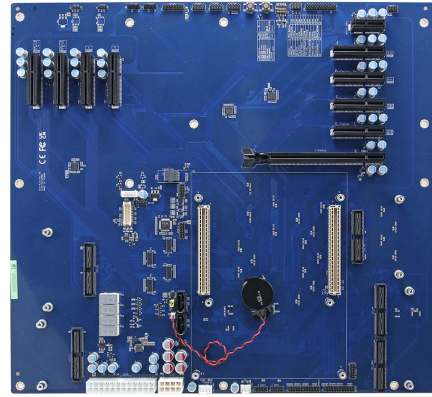


EEV-HC10

**COM-HPC Carrier Board in EATX Form Factor
(12" x 13", 305 x 330mm)**



Product Features

- EATX form factor (12" x 13", 305 x 330mm)
- Unmanaged COM-HPC Carrier (C.U.)
- 3 x DDI configurable to DP1.4a or HDMI 2.1b by 2x IET module, 1 x eDP
- 2 x 2.5 Gigabit Ethernet connector + 4 x USB3.2 Gen2x2 (Type C) by 2x IET module
- 2 x SATAIII
- PICMG®COM-HPC® Revision 1.2, COM-HPC client pin-out, size A(95x120mm), B(120x120mm), and C(160x120mm) compatible
- 1 x PCIe16 Gen5 slot, 8 x PCIe4 slot , 1 x PCIe1 slot for BMC
- 2 x 10 or 25 Gigabit Ethernet connector by 1x IET module
- 4 x USB2.0 by pin header
- 12-bit GPIO

Specification

System Information

Processor EATX form factor (12" x 13", 305 x 330mm), PICMG®COM-HPC® Revision 1.2, COM-HPC client pin-out, size A(95x120mm), B(120x120mm), and C(160x120mm) compatible

Expansion

Expansion 1 x PCIe16 Gen5 slot
8 x PCIe4 slot
1 x PCIe1 slot for BMC

Display

Multiple Display Depends on the COM-HPC module

DDI 3 x DDI configurable to DP2.1 or HDMI 2.1b by 2x IET module
1 x eDP

Audio

Audio Codec Realtek ALC888S HD Audio Decoding Controller

Audio Interface	Line-out, Mic-in
Ethernet	
Ethernet Interface	2 x 10 or 25 Gigabit Ethernet connector by 1x IET module 2 x 2.5 Gigabit Ethernet connector by 2x IET module
Software Support	
OS	According to COM-HPC Module Solution
Certification	
Certification Information	CE, FCC, RoHS Compliant
I/O	
USB	4 x USB3.2 Gen2x2 (Type C) by 2x IET module 4 x USB2.0 by pin header
GPIO	12-bit GPIO
UART	2 x Serial Port (2-wire UART)
Mechanical & Environmental	
Operating Temp.	0°C ~ 60°C (32°F ~ 140°F) with 0.5m/s air flow
Storage Temp.	-20°C ~ 75°C (-4°F ~ 167°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
Dimension (L x W)	12" x 13" (305 x 330mm)
Ordering Information	
Ordering Information	TBD